

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
23 February 2006 (23.02.2006)

PCT

(10) International Publication Number
WO 2006/019460 A3

(51) International Patent Classification:

F28F 7/00 (2006.01) *H01L 23/28* (2006.01)
H01L 23/495 (2006.01) *H01L 21/50* (2006.01)
H01L 23/10 (2006.01) *H01L 21/44* (2006.01)

(21) International Application Number:

PCT/US2005/018863

(22) International Filing Date: 27 May 2005 (27.05.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

10/891,648 15 July 2004 (15.07.2004) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA,
MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ,
OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL,
SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC,
VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,
SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

(88) Date of publication of the international search report:
14 September 2006

For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF ASSEMBLING A SEMICONDUCTOR COMPONENT AND APPARATUS THEREFOR

(57) Abstract: A method of assembling a semiconductor component includes providing a pedestal (61), placing a first piece (52) on the pedestal, wherein the first piece comprises a semiconductor die (54), placing a second piece (56, 58) over the first piece, and providing an adhesive (60) between the first piece and the second piece. The method further includes applying pressure with a first plate to the first piece and second piece to snap the first piece with the second piece, and applying heat with a second plate to reflow the adhesive, wherein applying heat is performed simultaneously with applying pressure.

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